

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Steven Webster, Thomas P. Glenn, Roy Dale Hollaway

Assignee: Amkor Technology, Inc.

Title: OPTICAL MODULE WITH LENS INTEGRAL HOLDER  
FABRICATION METHOD

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Assistant Commissioner for Patents  
Box PATENT APPLICATION  
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Dear Sir:

Prior to examination of the above-identified application,  
please amend the application as follows.

IN THE CLAIMS

Please add new Claims 26-30 as follows:

- 26. A method of forming an optical module comprising:  
coupling an image sensor to a base of a substrate;  
forming a bond between a first surface of a mounting  
surface of a lens housing and a joint surface of a sidewall of  
said substrate; and  
forming a bond between a second surface of said mounting  
surface and an interior surface of said sidewall.

27. A method of forming an optical module comprising:  
coupling an image sensor to a base of a substrate;

forming a bond between a first surface of a mounting surface of a lens housing and a joint surface of a sidewall of said substrate, said first surface of said mounting surface being parallel to said joint surface; and

forming a bond between a second surface of said mounting surface and an interior surface of said sidewall, said second surface of said mounting surface being perpendicular to said joint surface.

28. A method of forming an optical module comprising:  
coupling an image sensor to a base of a substrate;  
forming a bond between a first surface of a joint surface of a sidewall of said substrate and a mounting surface of a lens housing; and  
forming a bond between a second surface of said joint surface and an exterior side surface of said lens housing.

29. A method of forming an optical module comprising:  
coupling an image sensor to a base of a substrate;  
forming a bond between a first surface of a joint surface of a sidewall of said substrate and a mounting surface of a lens housing, said first surface of said joint surface being parallel to said mounting surface; and  
forming a bond between a second surface of said joint surface and an exterior side surface of said lens housing, said second surface of said joint surface being perpendicular to said mounting surface.

30. A method of forming an optical module comprising:  
coupling an image sensor to a base of a first substrate of an image sensor substrate;  
coupling a lens housing to said first substrate comprising:  
forming a bond between a first surface of a mounting surface of said lens housing and a joint surface of a first sidewall of said first substrate; and

forming a bond between a second surface of said mounting surface and an interior surface of said first sidewall; and

snapping said image sensor substrate along a singulation street between said first sidewall of said first substrate and a second sidewall of a second substrate of said image sensor substrate.--

REMARKS

New Claims 26-30 have been added. Support for Claims 26-30 appears in the specification at least at page 2, line 9 to page 30, line 30 and in FIGS. 1-12B.

Claims 1-30 are pending in this application. If the Examiner has any questions relating to the above, the Examiner is respectfully requested to telephone the undersigned Attorney for Applicants.

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Respectfully submitted,



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